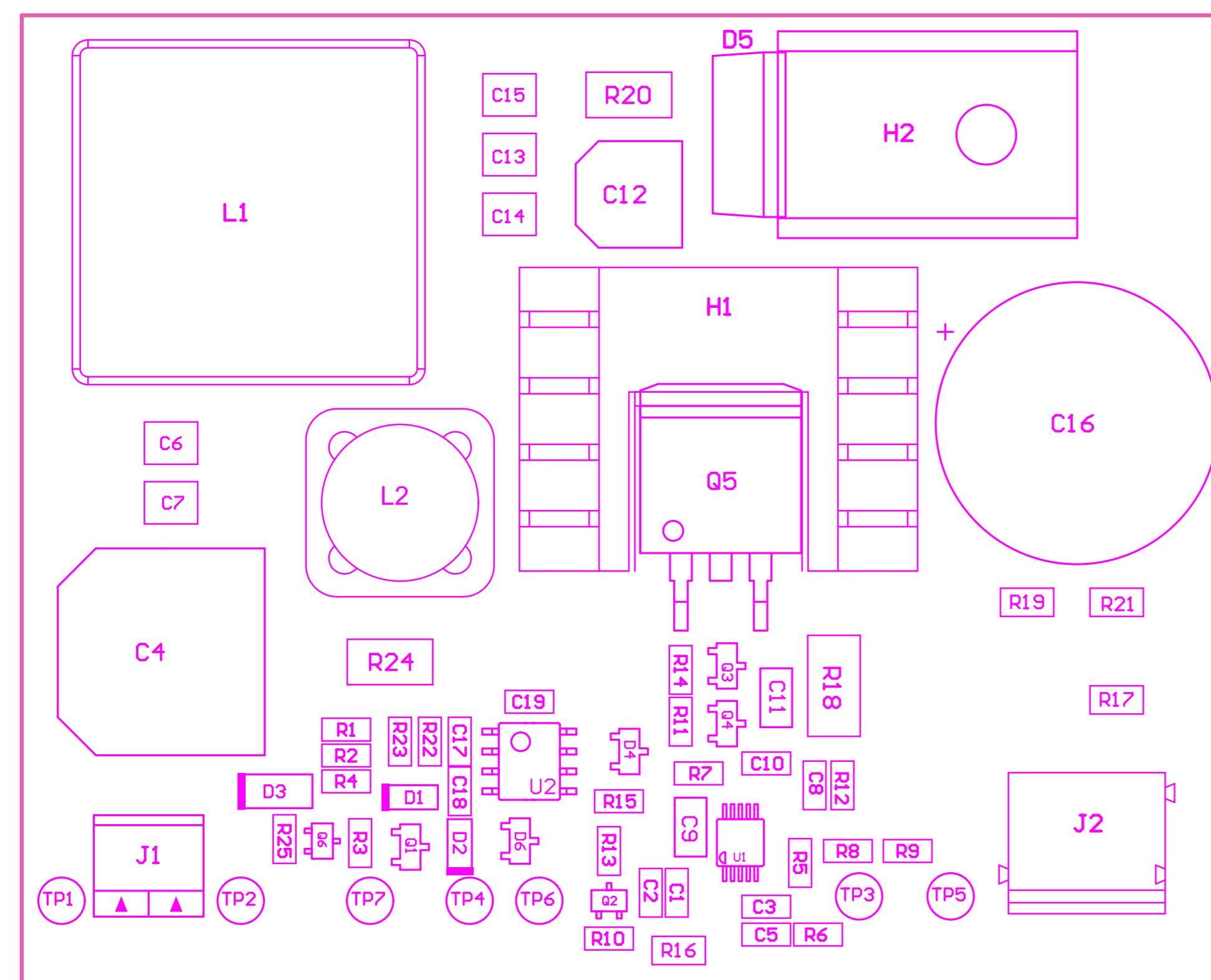
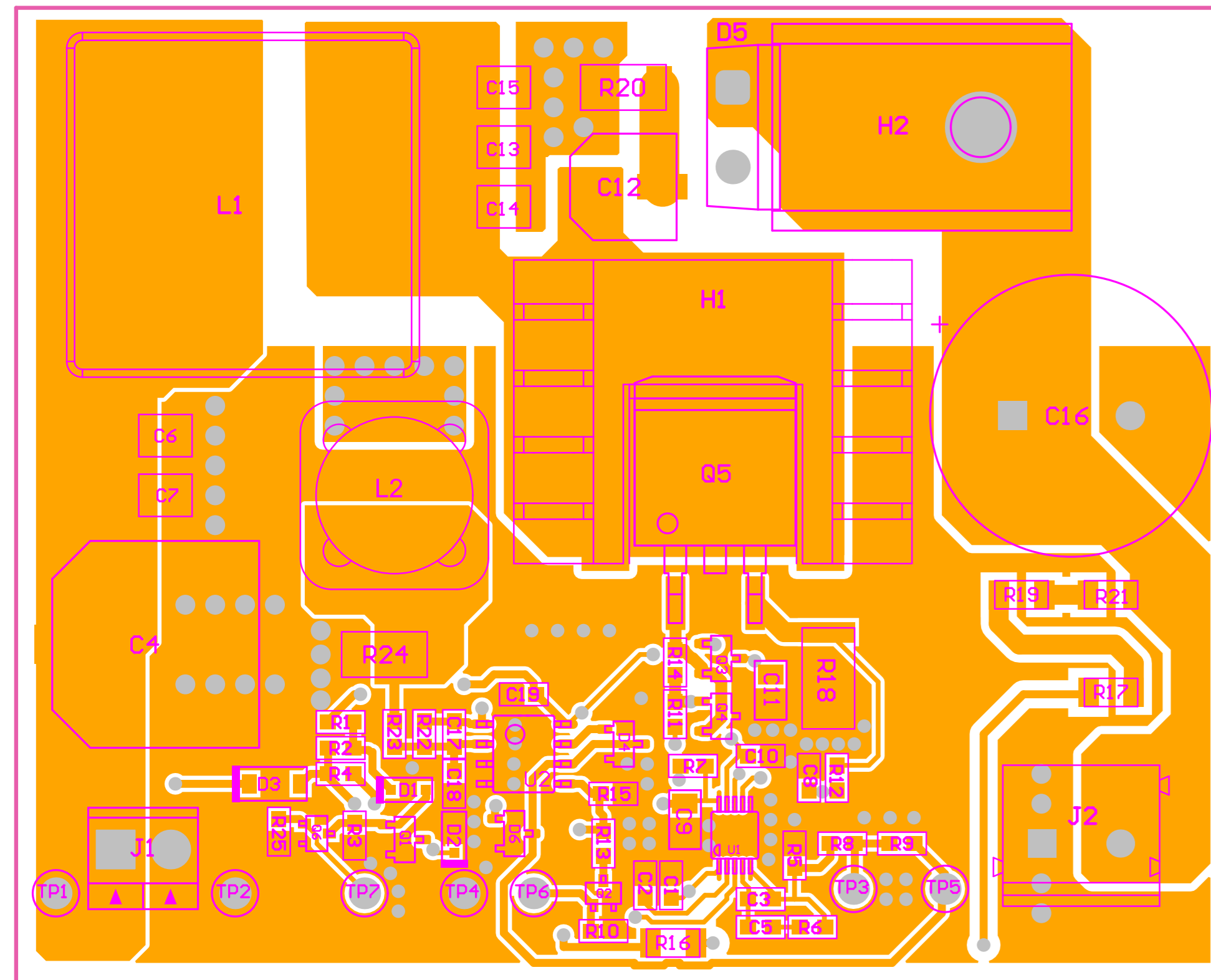


The Reference design PMP30162 Revision B has been built on PMP30162 Revision A PCB.



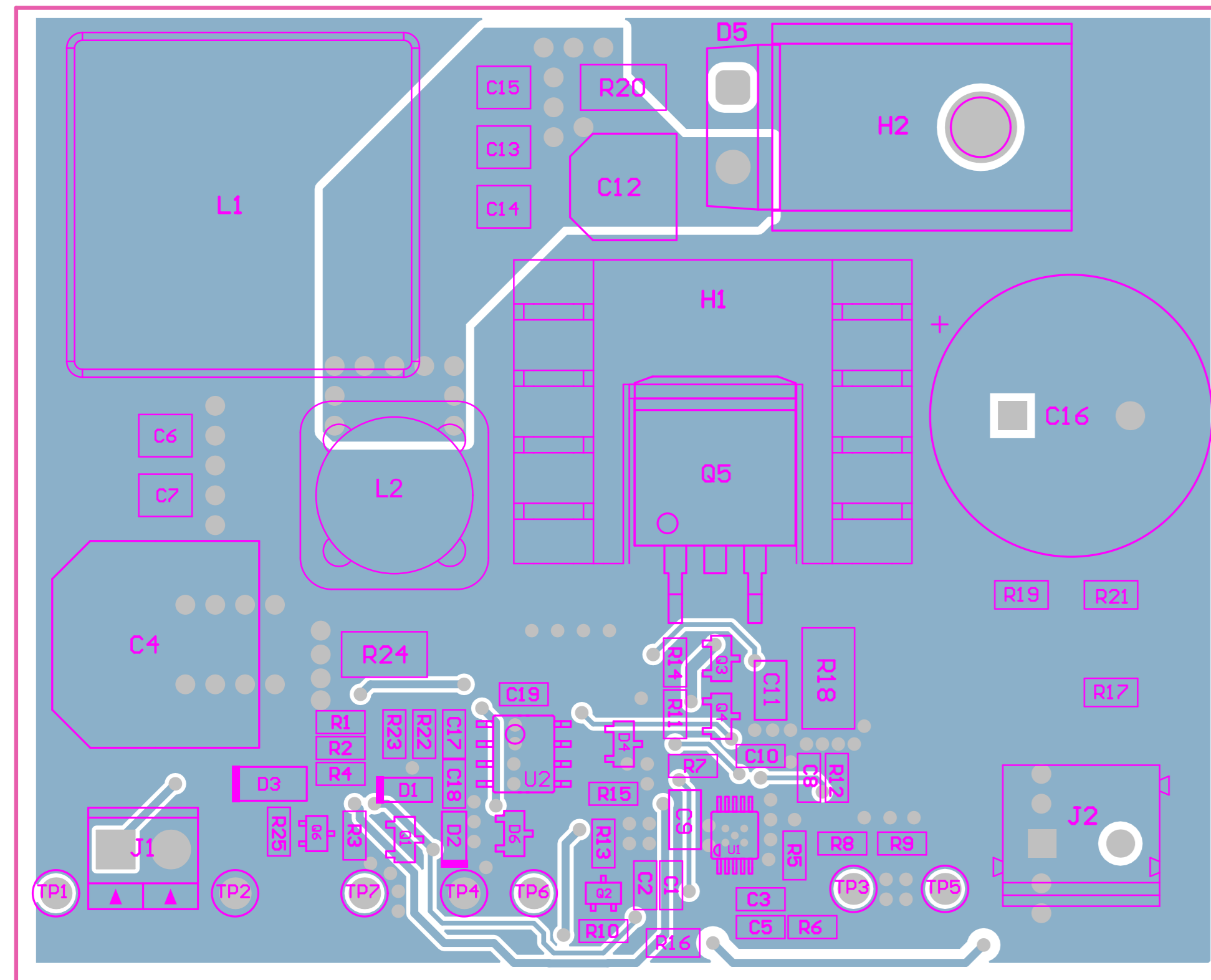
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP30162	REV:	SUN REV: Not In VersionControl
M1 Board Outline	TID #: .TID		
PLOT NAME = Assembly Layer	GENERATED : 11/23/2016 2:44:05 PM	TEXAS INSTRUMENTS	



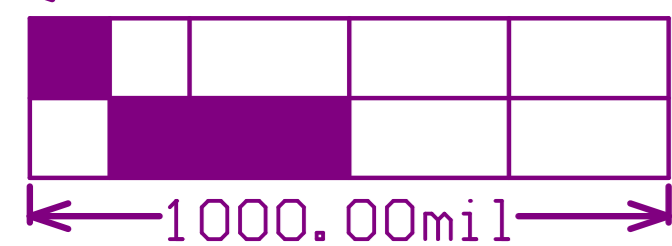
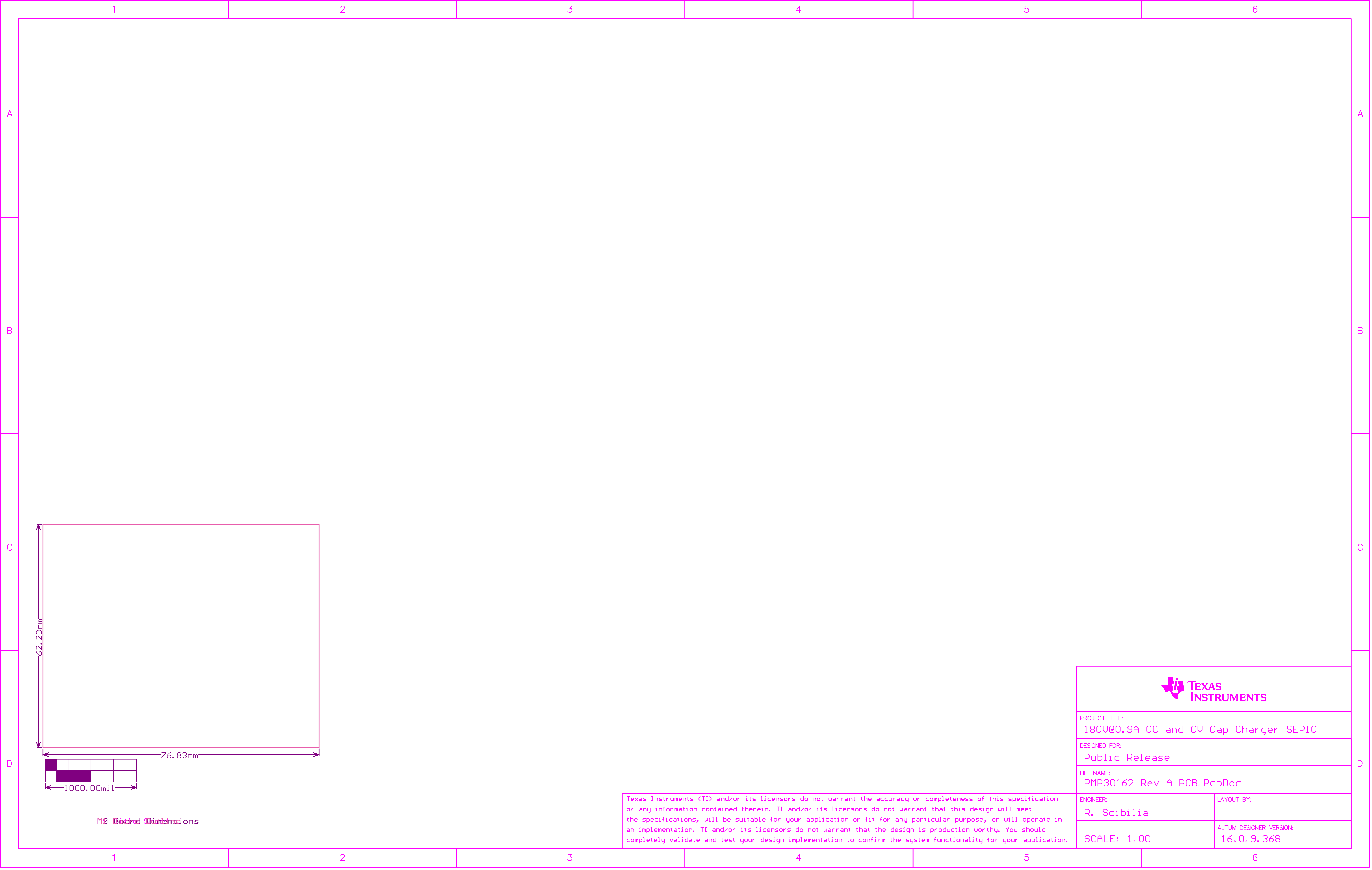
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP30162	REV:	SUN REV: Not In VersionControl
mhpBbagerOutline	TID #: .TID		
PLOT NAME = New PrintOut 1	GENERATED : 11/23/2016 2:44:05 PM		TEXAS INSTRUMENTS




COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP30162	REV:	SUN REV: Not In VersionControl
BoardOutline	TID #: .TID		
PLOT NAME = New PrintOut 1	GENERATED : 11/23/2016 2:44:05 PM	TEXAS INSTRUMENTS	



M2 Board Dimensions

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PROJECT TITLE: 180V@0.9A CC and CV Cap Charger SEPIC	
DESIGNED FOR: Public Release	
FILE NAME: PMP30162_Rev_A_PCB.PcbDoc	
ENGINEER: R. Scibilia	LAYOUT BY:
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

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